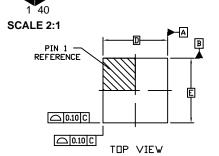
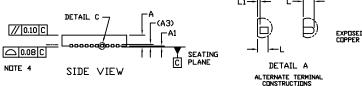


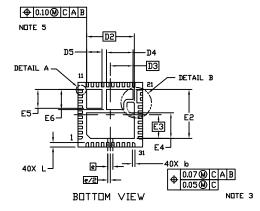
**DATE 26 APR 2016** 

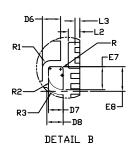


- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
- 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- POSITIONAL TOLERANCE APPLIES TO ALL OF THE EXPOSED PADS IN BOTH THE X AND Y AXIS.



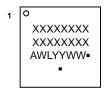






	MILLIMETERS		
DIM	MIN.	MAX.	
Α	0.80	1.00	
A1		0.05	
А3	0.20	REF	
b	0.15	0.25	
D	5.00	BSC	
D2	3.70	BSC	
D3	1.75	BSC	
D4	2.00	2.10	
D5	1.15	1.25	
D6	0.65	0.75	
D7	0.57 REF		
D8	0.63 REF		
E	5.00 BSC		
E2	3.75	3.85	
E3	1.85	BSC	
E4	1.95	2.05	
E5	1.40	1.50	
E6	1.50	1.60	
E7	0.89	0.89 REF	
E8	0.96	REF	
e	0.40	B2C	
L	0.25	0.45	
L1		0.15	
L2	0.35	0.55	
L3	0.10	0.30	
R	R0.10	REF	
R1	R0.30 REF		
R2	R0.55 REF		
R3	R0.75 REF		

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code

= Assembly Location

WL = Wafer Lot YY = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

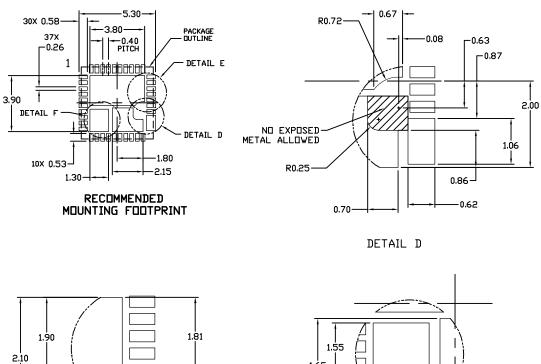
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

## **SOLDERING FOOTPRINT AND VIEWS ON PAGE 2**

DOCUMENT NUMBER:	98AON95304F	Electronic versions are uncontrolle	•	
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document versions are uncontrolled except	' '	
NEW STANDARD:		"CONTROLLED COPY" in red.		
DESCRIPTION:	QFN40, 5x5, 0.4P		PAGE 1 OF 3	

## QFN40 5x5, 0.4P CASE 485DY ISSUE A

**DATE 26 APR 2016** 



1.90	1.55
DETAIL E	DETAIL F

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<b>DOCUMENT</b>	NUMBER:
98AON95304	ŀF

PAGE 3 OF 3

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. P. FITZGERALD.	25 MAR 2015
A	UPDATED TO REFLECT NEW REV OF LEADFRAME IN USE FOR MULTI CHIP MODULES. UPDATED COD TO ADD COMMENT "NO EXPOSED METAL ALLOWED" UNDER THE LG INTERNAL PAD. REQ. BY P. FITZGERALD.	26 APR 2016

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